

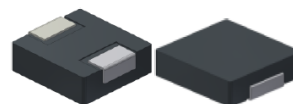
Molding Power Inductors

THMPI171707 Series

TOP-EMC

FEATURES

- Shielded construction
- Low loss realized with low DCR
- High performance (I_{sat}) realized by metal dust core.
- Ultra low buzz noise, due to composite construction.
- RoHS, Halogen Free and REACH Compliance
- High reliability -Reliability tests comply with AEC-Q200



APPLICATIONS

- Electric Power Steering
- ABS Control Units
- Battery powered devices
- Car Navigation Systems
- Meters/Alarms
- Car distance Control Units

PRODUCT IDENTIFICATION

THMPI
①

171707
②

D
③

2R2
④

M
⑤

T
⑥

- ① Type : THMPI
- ② External Dimensions (L×W×H) [mm]= 171707
- ③ Feature Type: Differential
- ④ Nominal Inductance : 2R2=2.2 μ H
- ⑤ Inductance Tolerance : K=±10%
M=±20%
N=±30%
- ⑥ Packing T=Tape Carrier Package

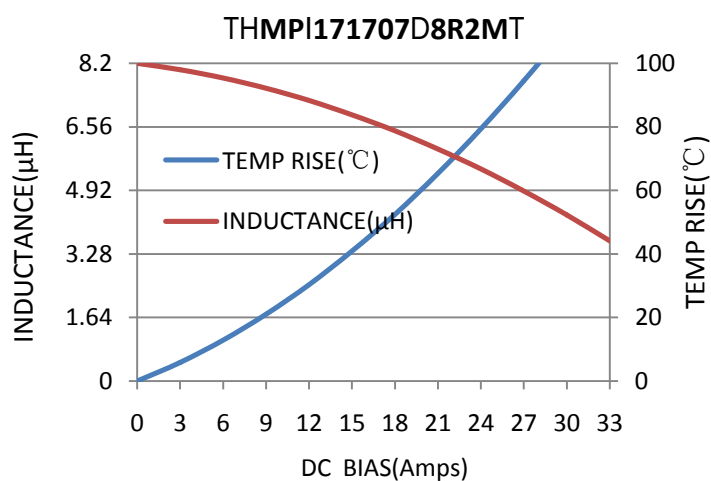
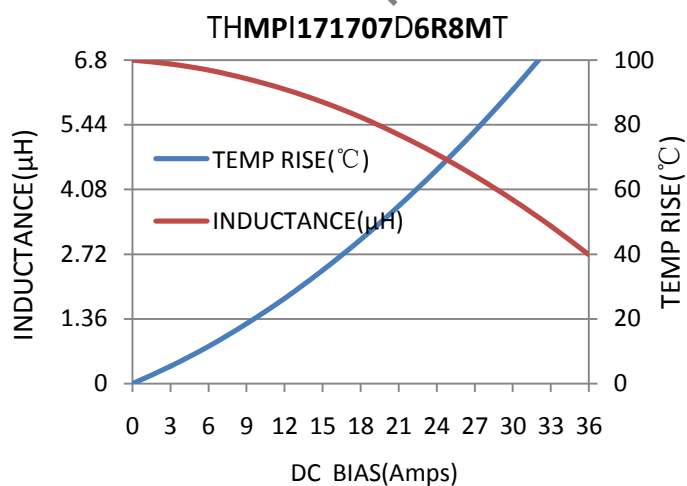
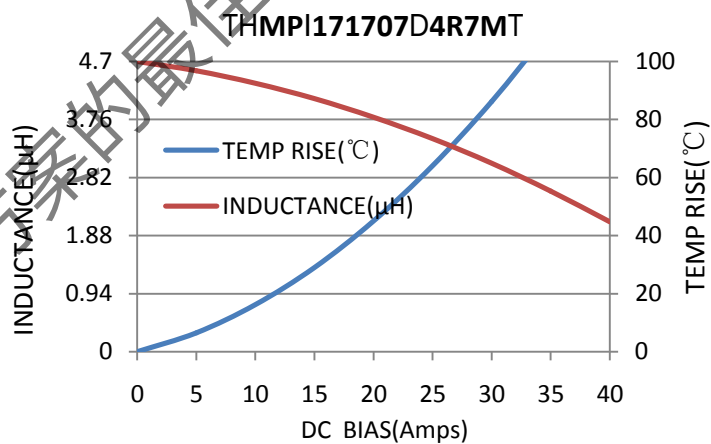
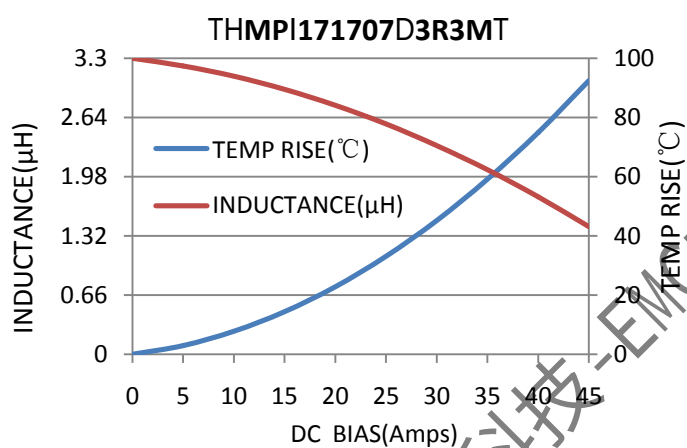
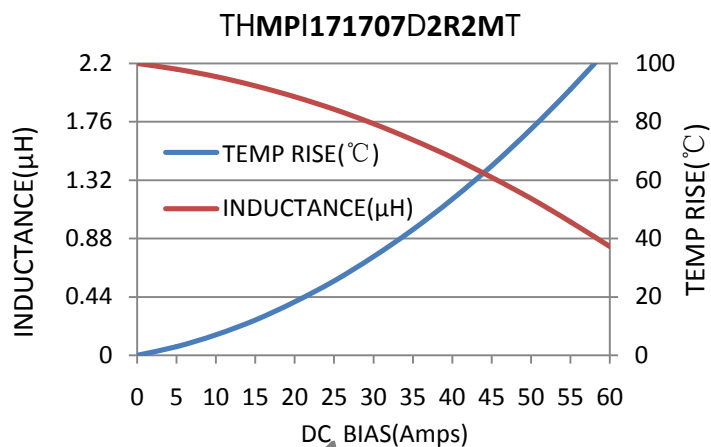
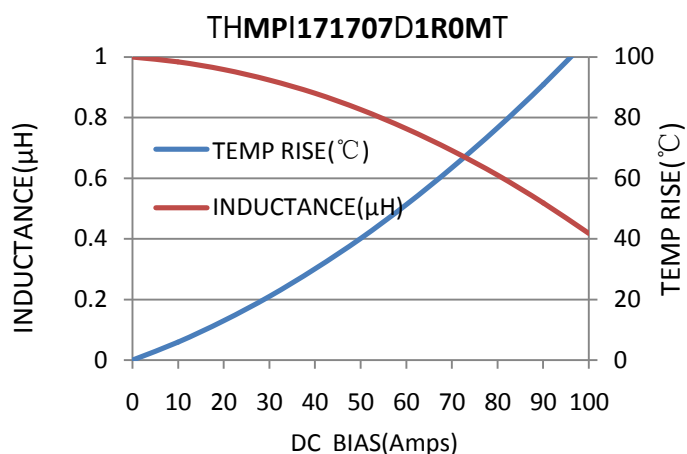
SPECIFICATIONS

Part No.	Inductance	DC Resistance		Heating Rating Current	Saturation Current
	L0 (μH) inductance@(0A)	DCR (mΩ)		Idc (A)	Isat (A)
	±20 %, 100 kHz, 1V	TYP.	MAX.	TYP.	TYP.
THMPI171707D1R0MT	1.0	1.3	1.5	42.0	62.0
THMPI171707D2R2MT	2.2	2.15	2.5	29.0	34.0
THMPI171707D3R3MT	3.3	2.79	2.93	24.5	27.0
THMPI171707D4R7MT	4.7	4.12	4.72	16.0	24.0
THMPI171707D6R8MT	6.8	6.55	7.55	14.0	22.0
THMPI171707D8R2MT	8.2	8.1	8.7	12.5	20.0
THMPI171707D100MT	10.0	9.3	10.0	11.0	18.0
THMPI171707D150MT	15.0	16.5	17.5	10.0	14.5
THMPI171707D200MT	20.0	19.5	21.9	9.5	12.0
THMPI171707D220MT	22.0	20.5	23.0	8.0	11.0
THMPI171707D330MT	33.0	35.1	37.0	7.0	10.0
THMPI171707D470MT	47.0	41.0	47.0	6.0	7.5
THMPI171707D680MT	68.0	74.0	85.0	5.5	6.5
THMPI171707D101MT	100.0	120.0	130.0	4.0	4.5

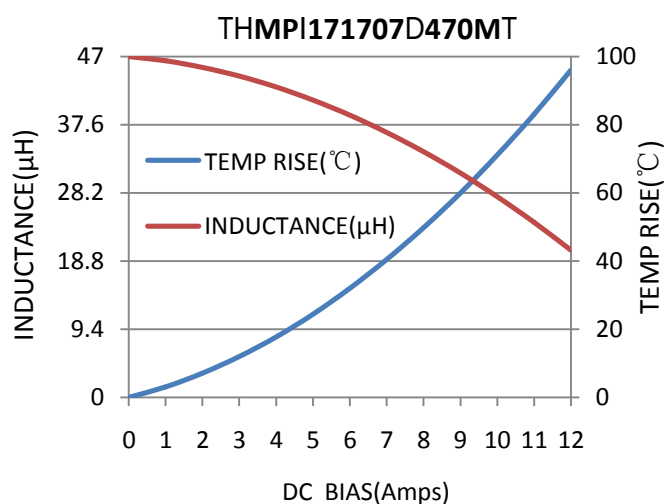
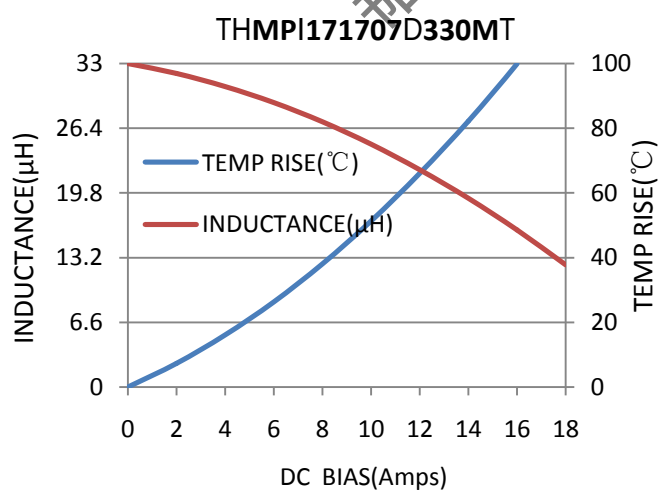
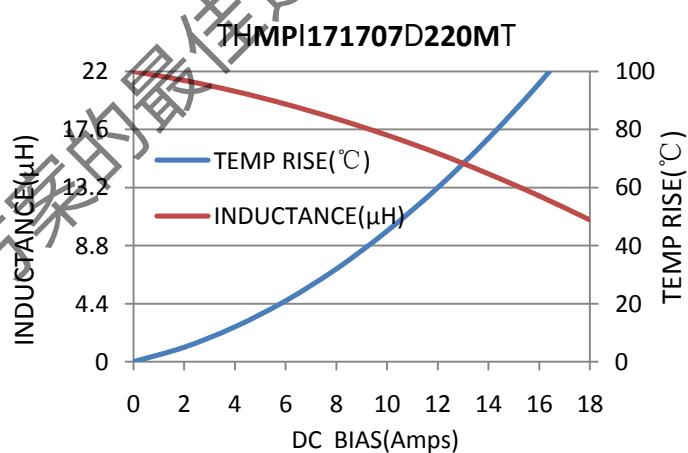
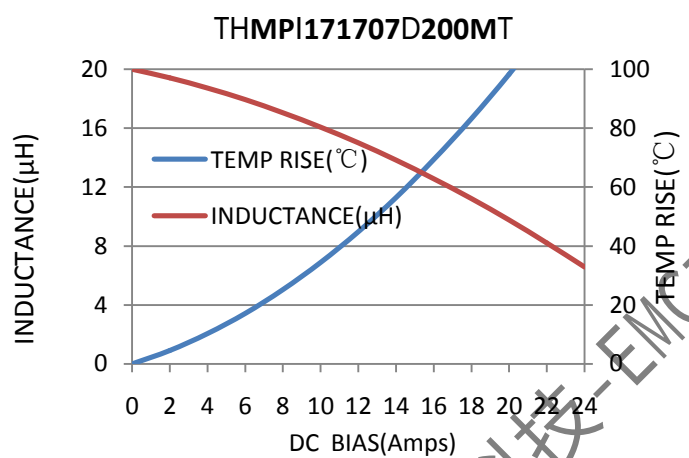
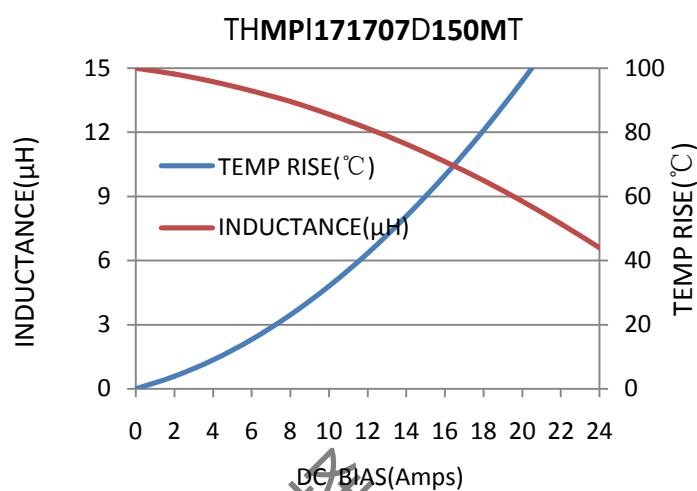
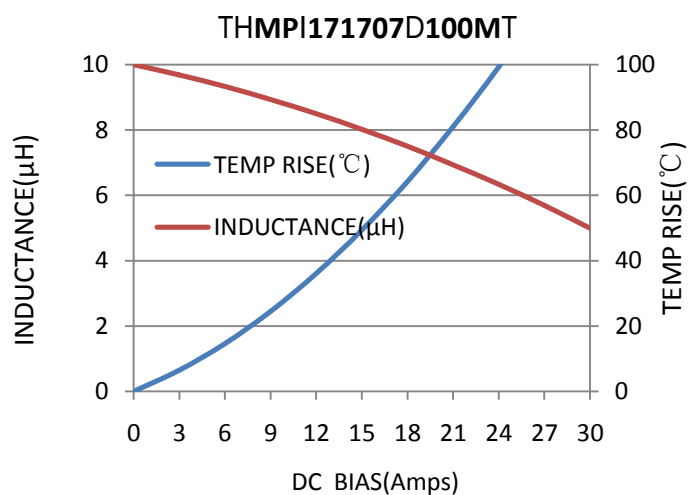
Notes

1. All test data is referenced to 25 °C ambient
2. Operating temperature range - 55 °C to + 125 °C
3. Idc(A):DC current (A) that will cause an approximate ΔT of 40 °C(reference ambient temperature is 25°C)
4. Isat(A):DC current (A) that will cause L0 to drop approximately 30 %
5. The part temperature (ambient + temp rise) should not exceed 125 °C under worst case operating conditions.
Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

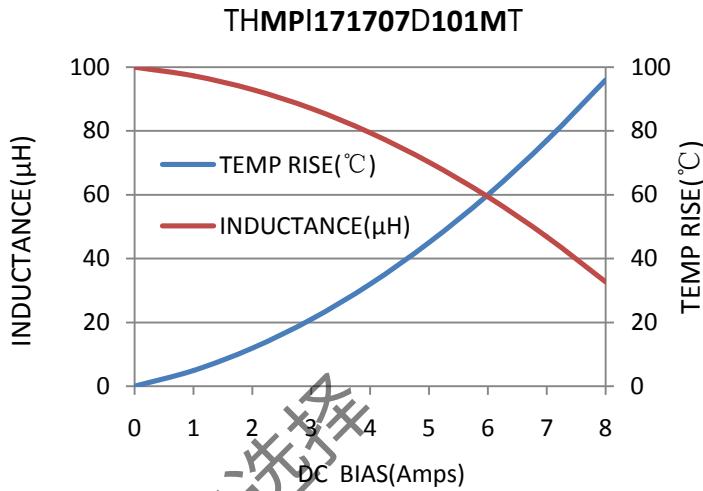
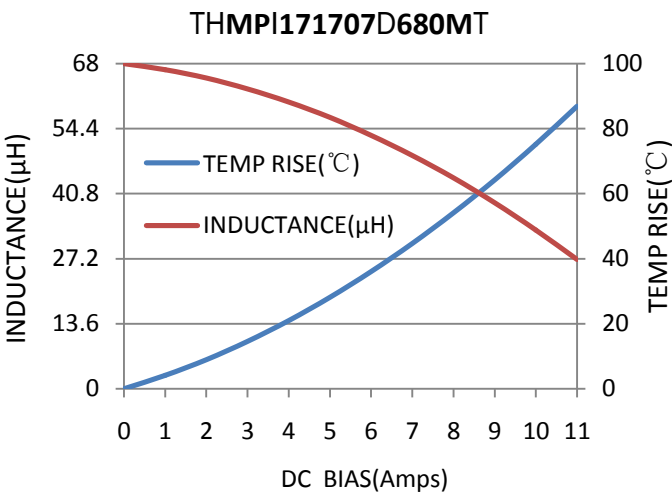
Graph



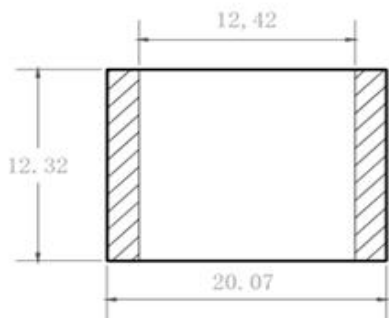
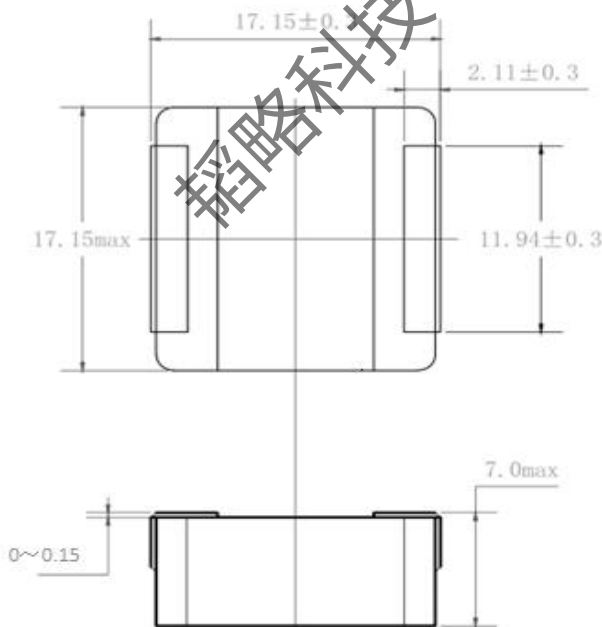
Graph



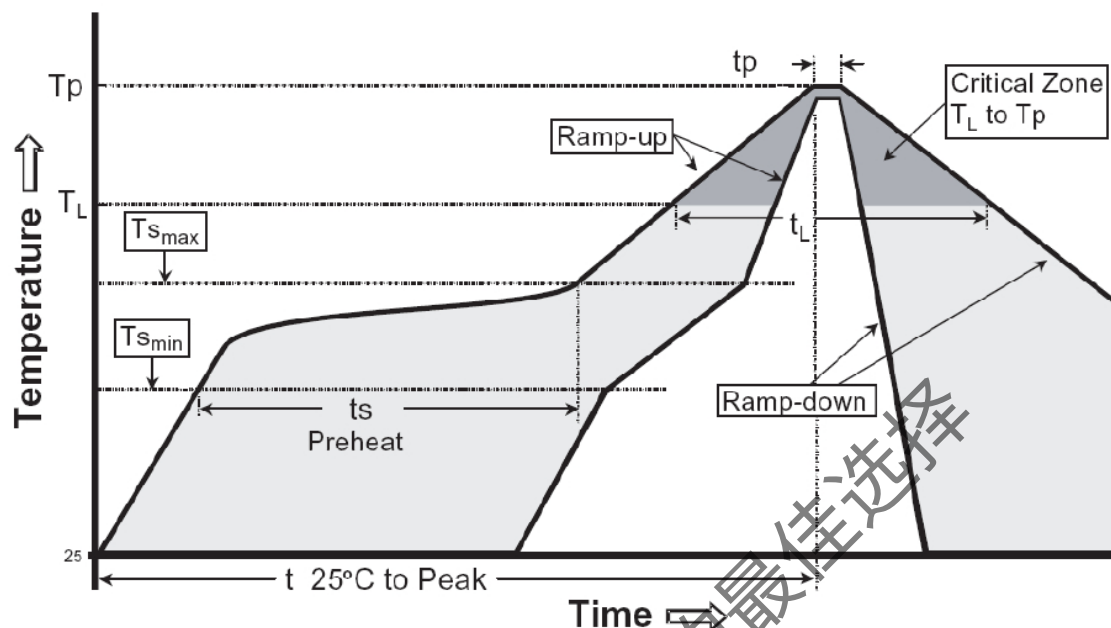
Graph



SHAPE AND DIMENSIONS (Dimensions in mm)



RECOMMENDED SOLDERING TECHNOLOGIES



Profile Feature	Pb free Assembly
Average Ramp Rate ($T_{s_{max}}$ to T_p)	3 °C/second max
Preheat - Temperature Min ($T_{s_{min}}$) - Temperature Min ($T_{s_{max}}$) - Time ($t_{s_{min}}$ to $t_{s_{max}}$)	150°C 200°C 60-180 seconds
Time maintained above: - Temperature (T_L) - Time (t_L)	217°C 60-150 seconds
Peak/Classification Temperature (T_p)	260 °C
Peak/Classification Time (T_p)	3-4 seconds
Time within 5 °C of actual Peak Temperature (T_p)	20-40 seconds
Ramp-Down Rate	6 °C/second max.
Time 25°C to Peak Temperature	8 minutes max

CONTACT INFORMATION

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